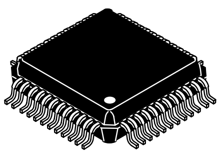
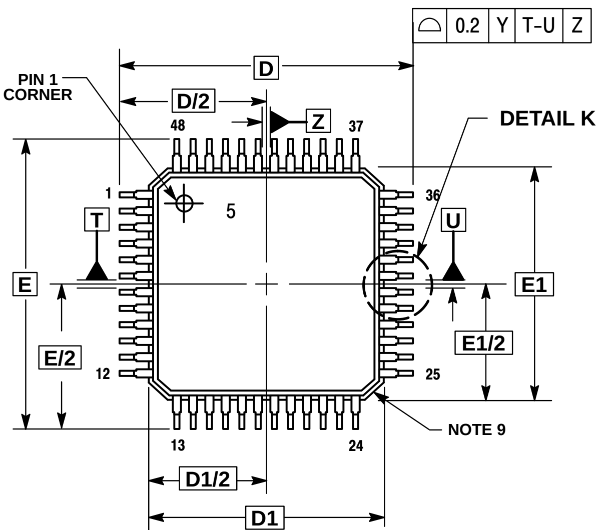
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

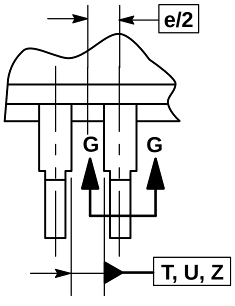
48 LEAD LQFP, 7x7, 0.5P
CASE 932AA
ISSUE A

DATE 13 OCT 2008

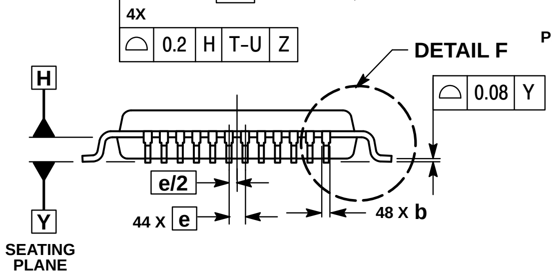


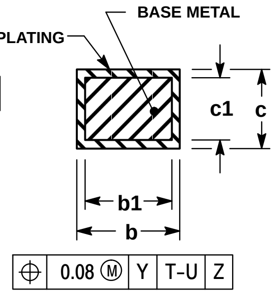
SCALE 2:1



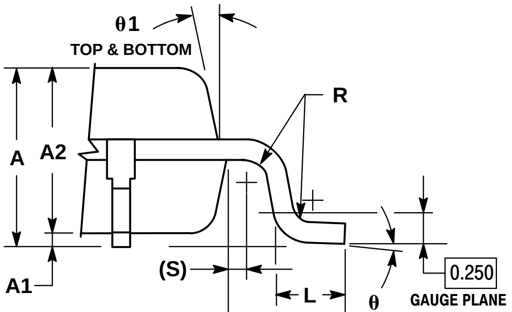


DETAIL K





SECTION G−G

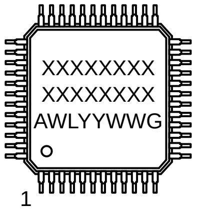


DETAIL F

NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DATUM PLANE H IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS T, U, AND Z TO BE DETERMINED AT DATUM PLANE H.
5. DIMENSIONS D AND E TO BE DETERMINED AT SEATING PLANE Y.
6. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 PER SIDE. DIMENSIONS D1 AND E1 DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
7. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE b DIMENSION TO EXCEED 0.350.
8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076.
9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

	MILLIMETERS	
DIM	MIN	MAX
A	1.4	1.6
A1	0.05	0.15
A2	1.35	1.45
b	0.17	0.27
b1	0.17	0.23
c	0.09	0.20
c1	0.09	0.16
D	9.0 BSC	
D1	7.0 BSC	
e	0.5 BSC	
E	9.0 BSC	
E1	7.0 BSC	
L	0.5	0.7
L1	1.0 REF	
R	0.15	0.25
S	0.2 REF	
θ	1 °	5 °
θ1	12 REF	

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

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DESCRIPTION:	**48 LEAD LQFP 7X7X1.4, 0.5 PITCH**	**PAGE 1 OF 1**